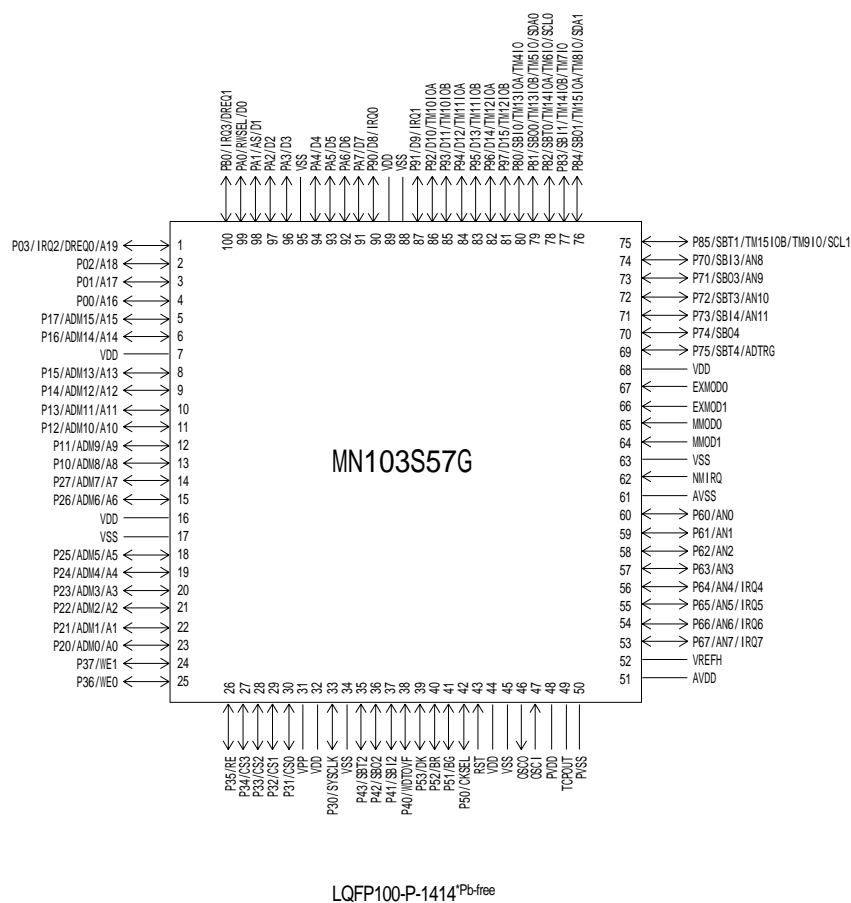


# **MN103S57G**

■ <b>Type</b>		MN103S57G (under development)	
■ <b>Command ROM (×64-bit)</b>		128 K-byte	
■ <b>Data RAM (×32-bit)</b>		16 K-byte	
■ <b>Package</b>		LQFP100-P-1414 *Pb-free	
■ <b>Minimum Instruction Execution Time</b>		25.0 ns (at 3.0 V to 3.6 V, 40 MHz)	
■ <b>Interrupts</b>		• RESET • IRQ × 8 • NMI • Timer × 28 • SIF × 10 • I <sup>2</sup> C × 2 • DMA × 12 • WDT • A/D • System error	
■ <b>Timer Counter</b>		8-bit timer × 10 Reload-down count Cascade connection possible (usable as a 16-bit to 32-bit timer)  16-bit timer × 6 Up-down count Input capture function PWM generating function Compare/capture register 2-ch.  Watchdog timer × 1	
■ <b>DMA Controller</b>		Number of channels: 4 Unit of transfer: 8/16/32 bits Max. Transfer cycles: 65535 Starting factor: external interrupt, timer factor, serial transmission/reception factor, I <sup>2</sup> C transmission/reception factor, external transmission request factor, A/D conversion finish, software factor Transfer method: 2-bus cycle transfer Addressing modes: fixed, increment, decrement Transfer modes: word transfer, burst transfer, intermittent transfer	
■ <b>Serial Interface</b>		UART/synchronous/multi-master I <sup>2</sup> C interface selective: 2 UART/synchronous interface selective: 3	
■ <b>I/O Pins</b>	<b>I/O</b>	73	• Common use
■ <b>A/D Inputs</b>		10-bit × 12-ch.	
■ <b>Electrical Characteristics</b>		T.B.D.	

## Pin Assignment



## SupportTool

<b>In-circuit Emulator</b>	PX-ICE103S57	
<b>On-board Development Tools</b>	PX-ODB103S-O	
<b>Flash Memory Built-in Type</b>	Type	MN103SF57G (under development)
	Command ROM (× 64-bit)	128 K-byte
	Data RAM (× 32-bit)	16 K-byte
	Minimum instruction execution time	25.0 ns (at 3.0 V to 3.6 V, 40 MHz)
	Package	LQFP100-P-1414A *Pb-free

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